TOSHIBA RECTIFIER SILICON DIFFUSED JUNCTION TYPE

# U1BC44,U1GC44,U1JC44

### FOR HYBRID USE

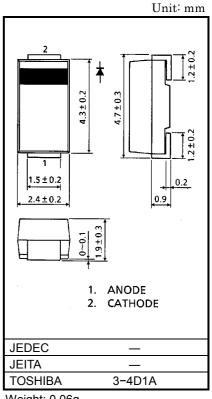
• Average Forward Current  $I_{F(AV)} = 1.0A$ 

• Repetitive Peak Reverse Voltage  $V_{RRM} = 100, 400, 600V$ 

Mini Plastic Mold Package

## MAXIMUM RATINGS (Ta = 25°C)

CHAR	RACTERIST	IC	SYMBOL	RATING	UNIT	
		U1BC44		100		
Repetitive Peak Reverse Voltage		U1GC44	$V_{RRM}$	400	V	
		U1JC44		600		
Average Forward	On Ceram	ic Substrate	I	1.0 (Ta = 75°C)	А	
Current	On Glass- Substrate	ероху	<sup>I</sup> F (AV)	0.9 (Ta = 25°C)		
Peak One Cycl	e Surge For	ward	l	30 (50Hz)	А	
Current (Non-F	Repetitive)		I <sub>FSM</sub>	33 (60Hz)	A	
Junction Tempe	erature		Tj	-40~150	°C	
Storage Tempe	erature Ranç	де	T <sub>stg</sub>	-40~150	°C	

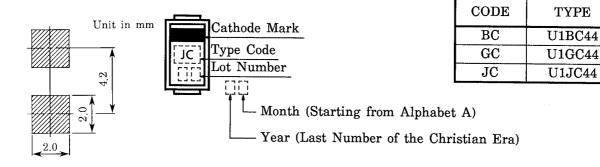


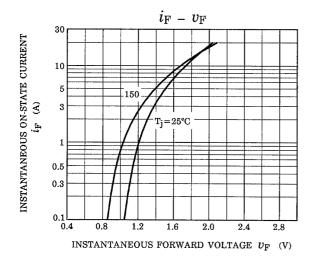
Weight: 0.06g

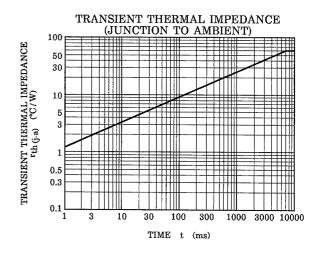
## **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC	SYMBOL		TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	$V_{FM}$	I <sub>FM</sub> = 1.0A		_	_	1.2	V
Repetitive Peak Reverse Current IRRM		V <sub>RRM</sub>	= Rated	_	_	10	μΑ
Thermal Resistance	R <sub>th (j-a)</sub>	DC	On ceramic substrate	_	_	60	°C/W
Thermal Nesislance			On glass-epoxy substrate	_	_	120	C / VV

#### STANDARD SOLDERING PAD

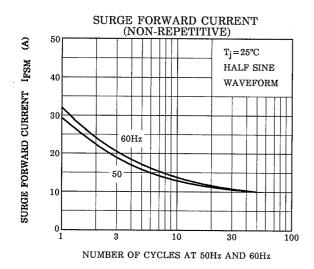






160											
					CER SSTR	AMI ATE	c _				
120				_							
80	]	ASS-E		XY.					/		
40											
0		 0.2	0.	.4	0	.6	0.	8	1.	0	

			ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
	Soldering land	: a□	$2 \mathrm{mm}^\square$	6mm <sup>□</sup>
	Substrate size	: b□	$50 \mathrm{mm}^\square$	50mm <sup>□</sup>
	Substrate thickness	: c□	0.64t	1.6t
A)			a	c



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#### **RESTRICTIONS ON PRODUCT USE**

Handbook" etc..

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